

Fig. 2A
(PRIOR ART)

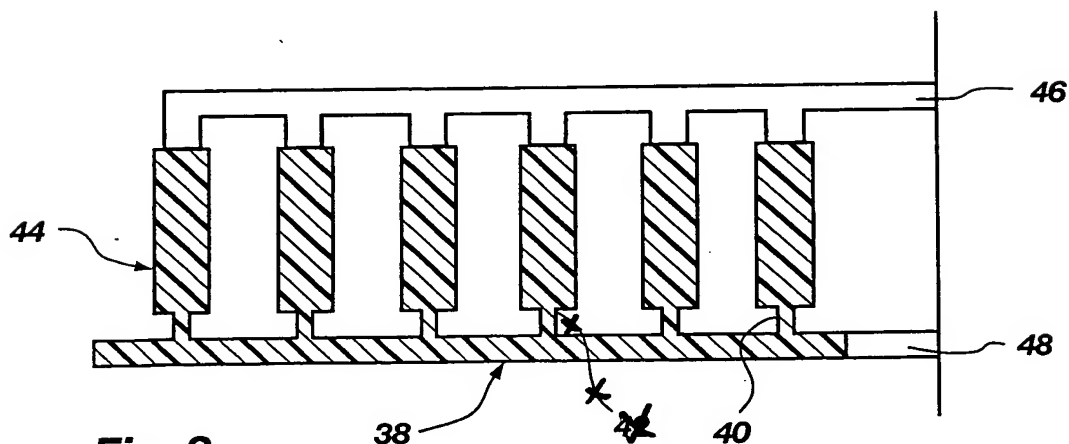
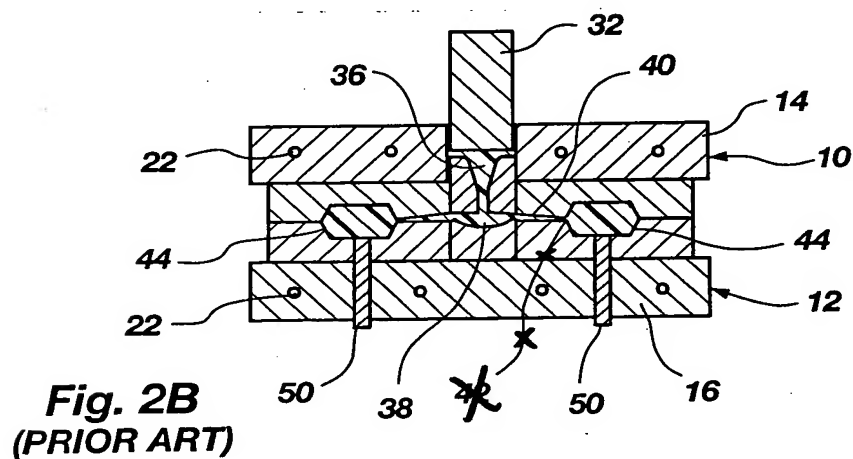


Fig. 3
(PRIOR ART)



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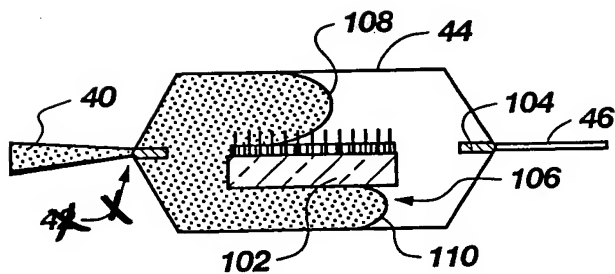


Fig. 4A
(PRIOR ART)

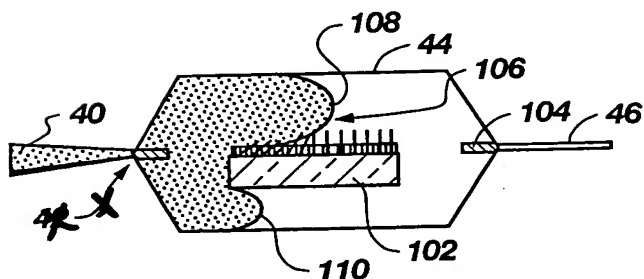


Fig. 4B
(PRIOR ART)

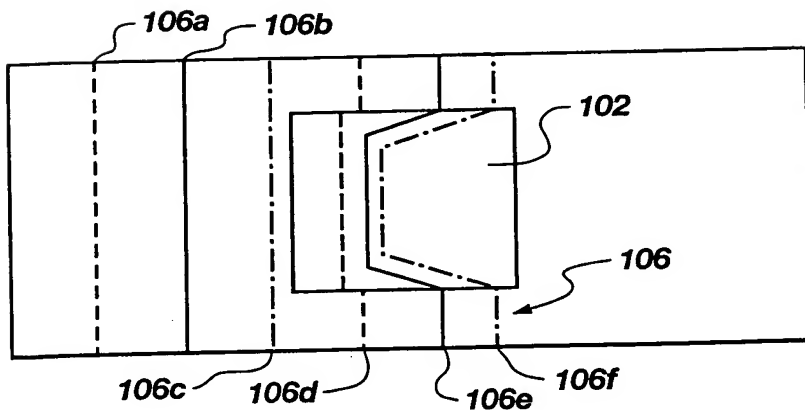


Fig. 4C
(PRIOR ART)

TITLE: METHOD AND APPARATUS FOR TRANSFER MOLDING
ENCAPSULATION OF A SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK

Inventor: Richard W. Wensel

Serial No.: 10/077,452

Docket No.: 3061.6US (96-0893.05/US)



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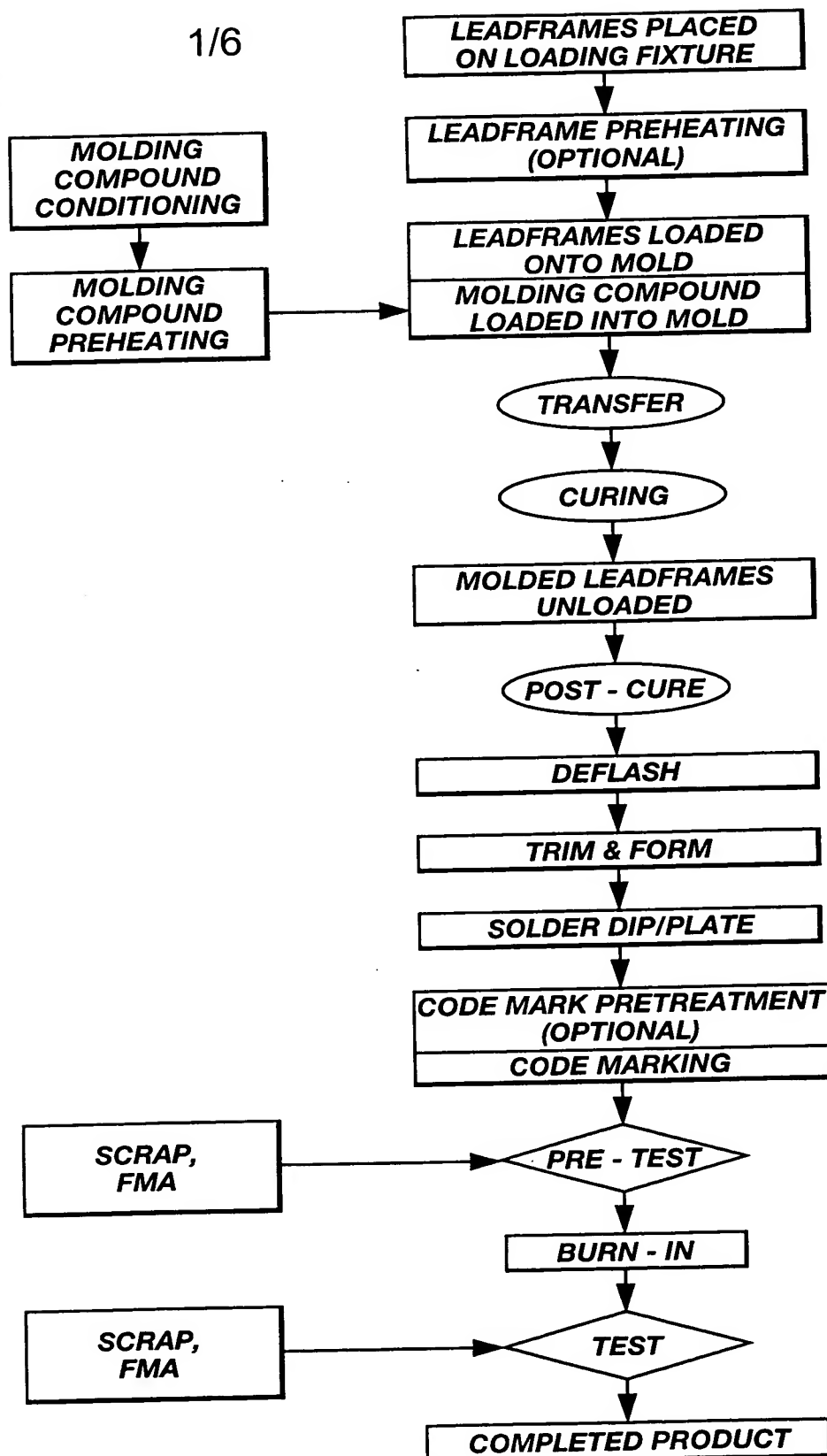


Fig. 1
(PRIOR ART)

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Serial No.: 10/077,452
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Docket No.: 3061.6US (96-0893.05/US)



Fig. 2A
(PRIOR ART)

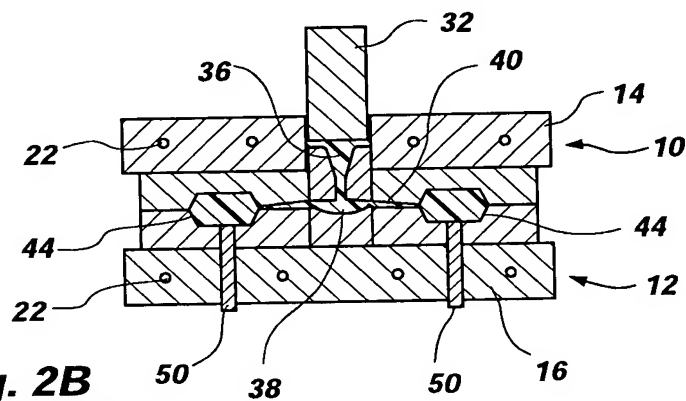


Fig. 2B
(PRIOR ART)

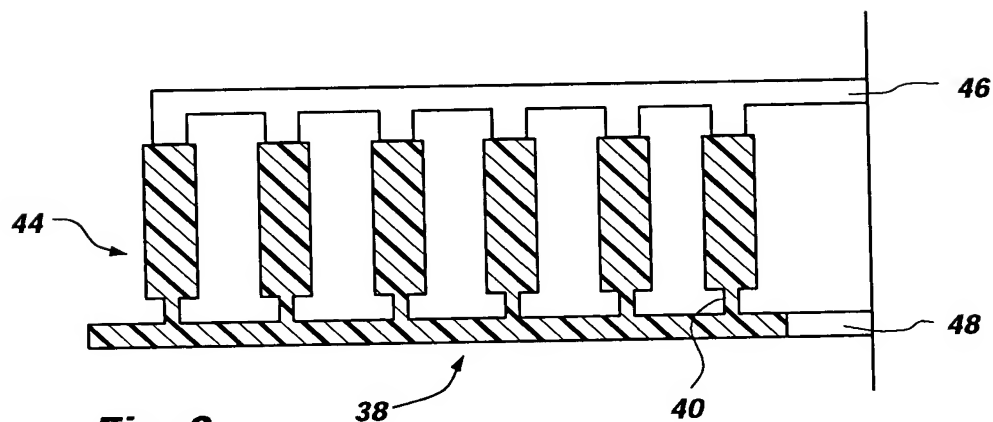


Fig. 3
(PRIOR ART)

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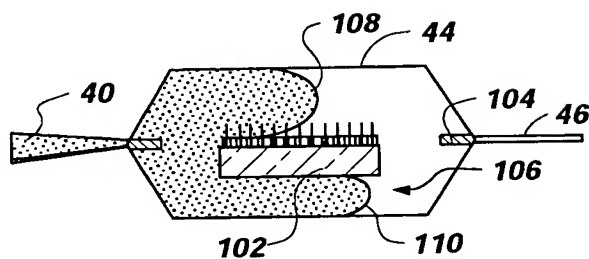


Fig. 4A
(PRIOR ART)

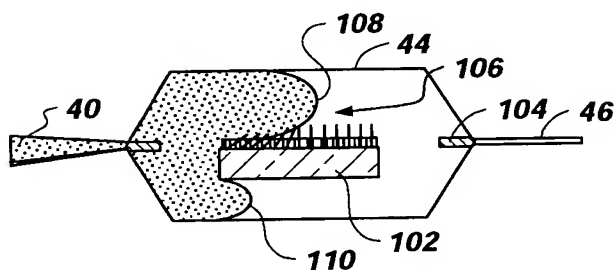


Fig. 4B
(PRIOR ART)

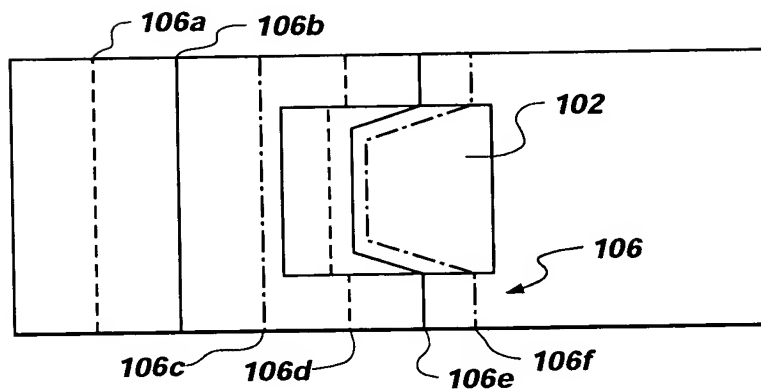


Fig. 4C
(PRIOR ART)



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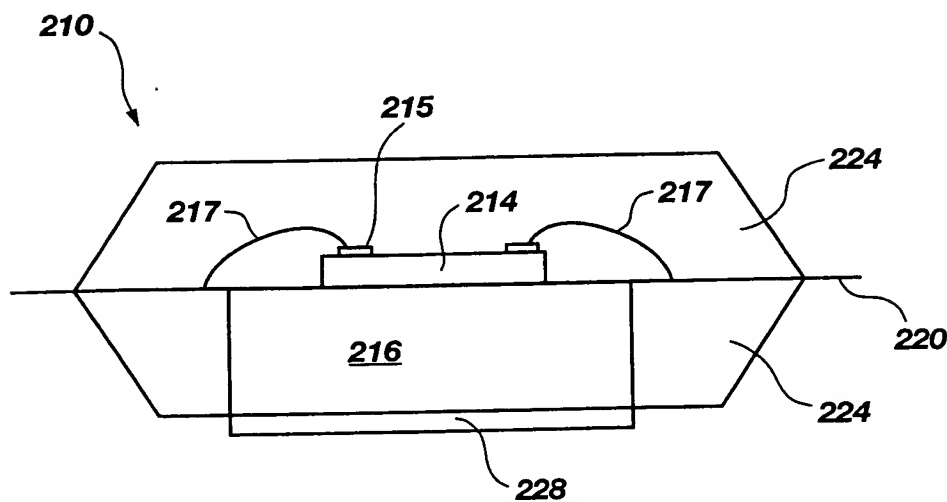


Fig. 5

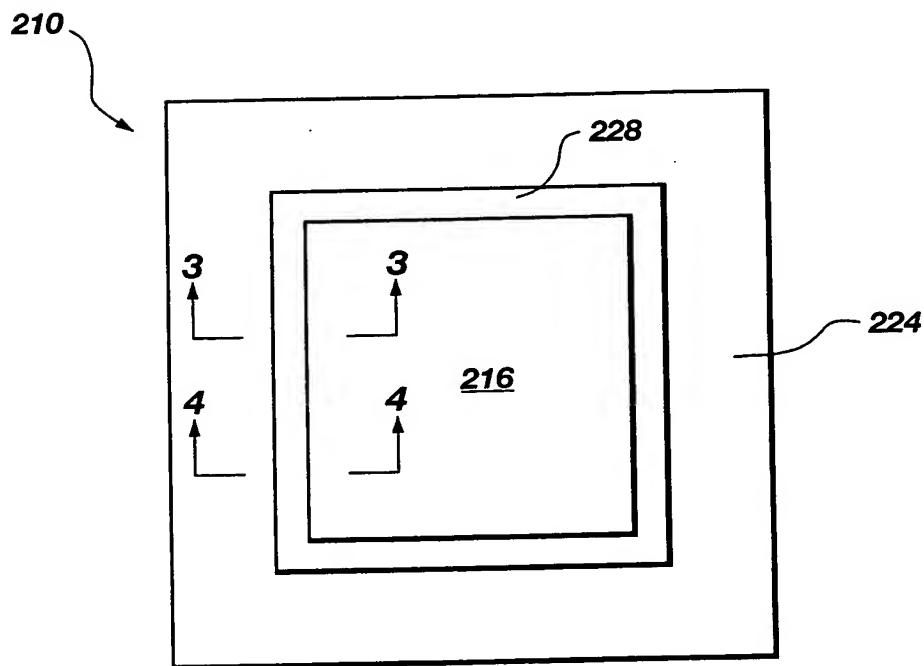


Fig. 6



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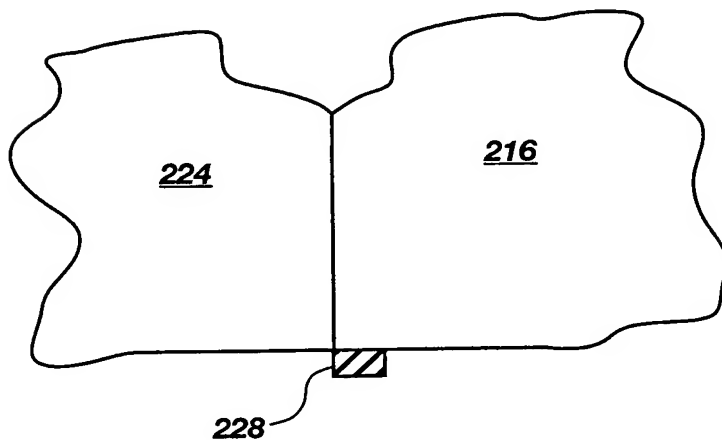


Fig. 7

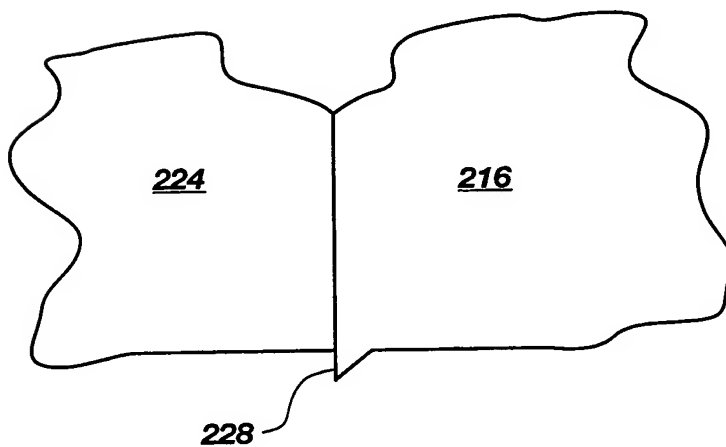


Fig. 8



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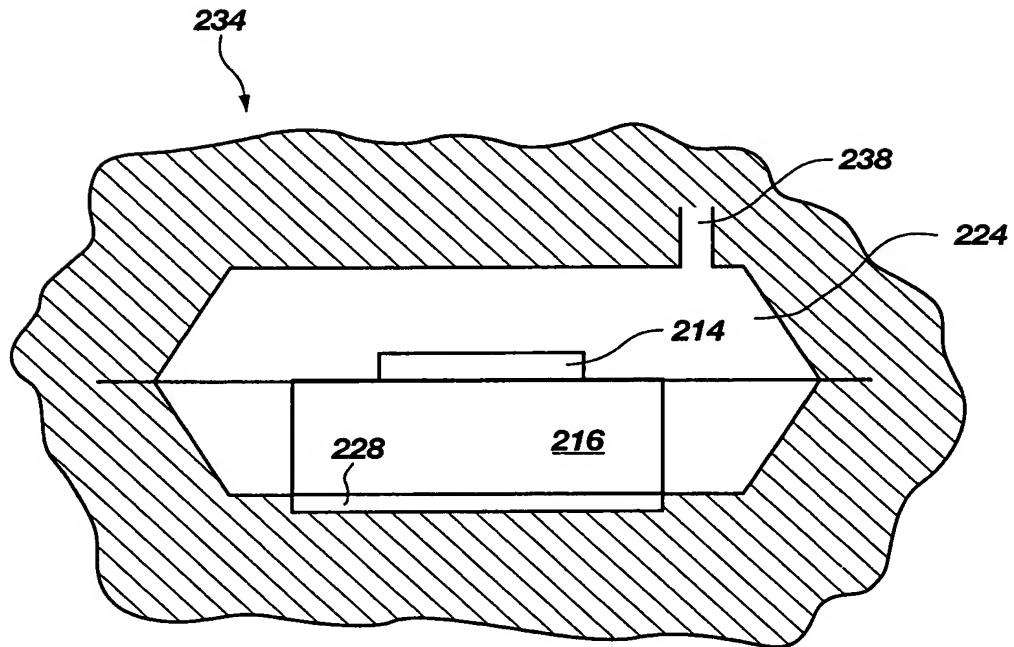


Fig. 9